

Selection Guide

| Part No. | Dice | Lens Type | Iv (mcd) [2] @ 20mA | | Viewing Angle [1] |
|-----------|----------------------|-------------|------------------------|------|----------------------|
| | | | Min. | Typ. | 2θ1/2 |
| AM27MGC08 | Mega Green (AlGaInP) | WATER CLEAR | 280 | 600 | 20° |

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

| Symbol | Parameter | Device | Typ. | Max. | Units | Test Conditions |
|--------|--------------------------|------------|------|------|-------|-----------------|
| λpeak | Peak Wavelength | Mega Green | 574 | | nm | IF=20mA |
| λD [1] | Dominant Wavelength | Mega Green | 570 | | nm | IF=20mA |
| Δλ1/2 | Spectral Line Half-width | Mega Green | 26 | | nm | IF=20mA |
| C | Capacitance | Mega Green | 20 | | pF | VF=0V;f=1MHz |
| VF [2] | Forward Voltage | Mega Green | 2.1 | 2.5 | V | IF=20mA |
| IR | Reverse Current | Mega Green | | 10 | uA | VR=5V |

Notes:

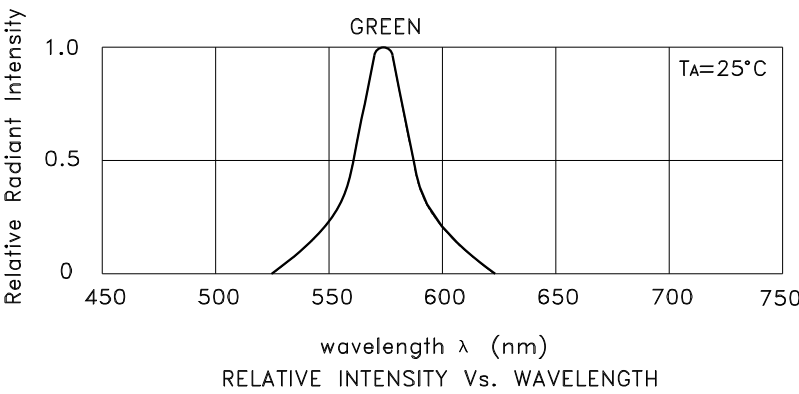
- 1.Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

| Parameter | Mega Green | Units |
|--------------------------|----------------|-------|
| Power dissipation | 75 | mW |
| DC Forward Current | 30 | mA |
| Peak Forward Current [1] | 150 | mA |
| Reverse Voltage | 5 | V |
| Operating Temperature | -40°C To +85°C | |
| Storage Temperature | -40°C To +85°C | |

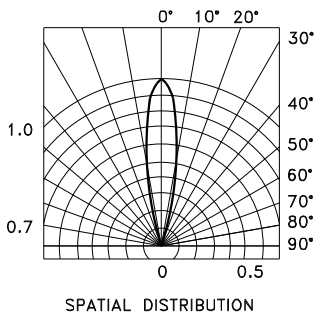
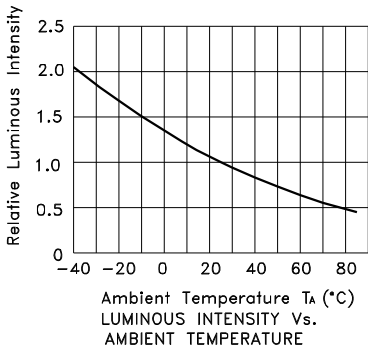
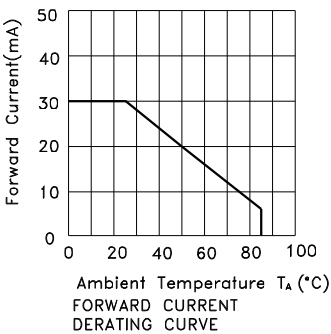
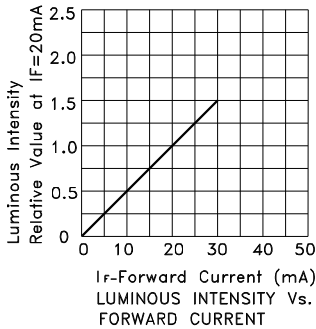
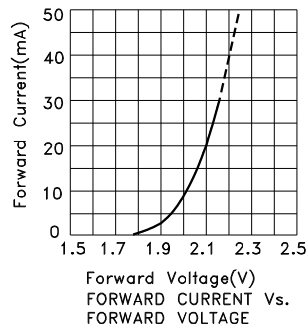
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



Mega Green

AM27MGC08



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Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

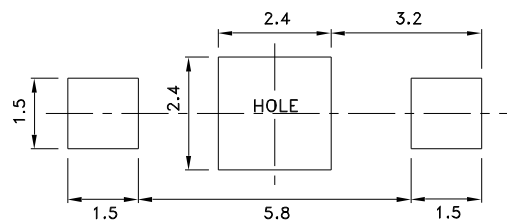
Reflow Soldering Profile For Lead-free SMT Process.



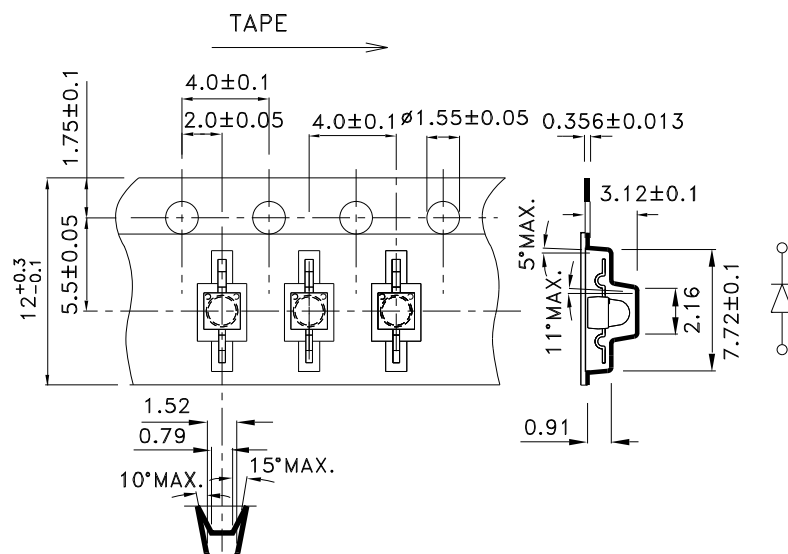
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)

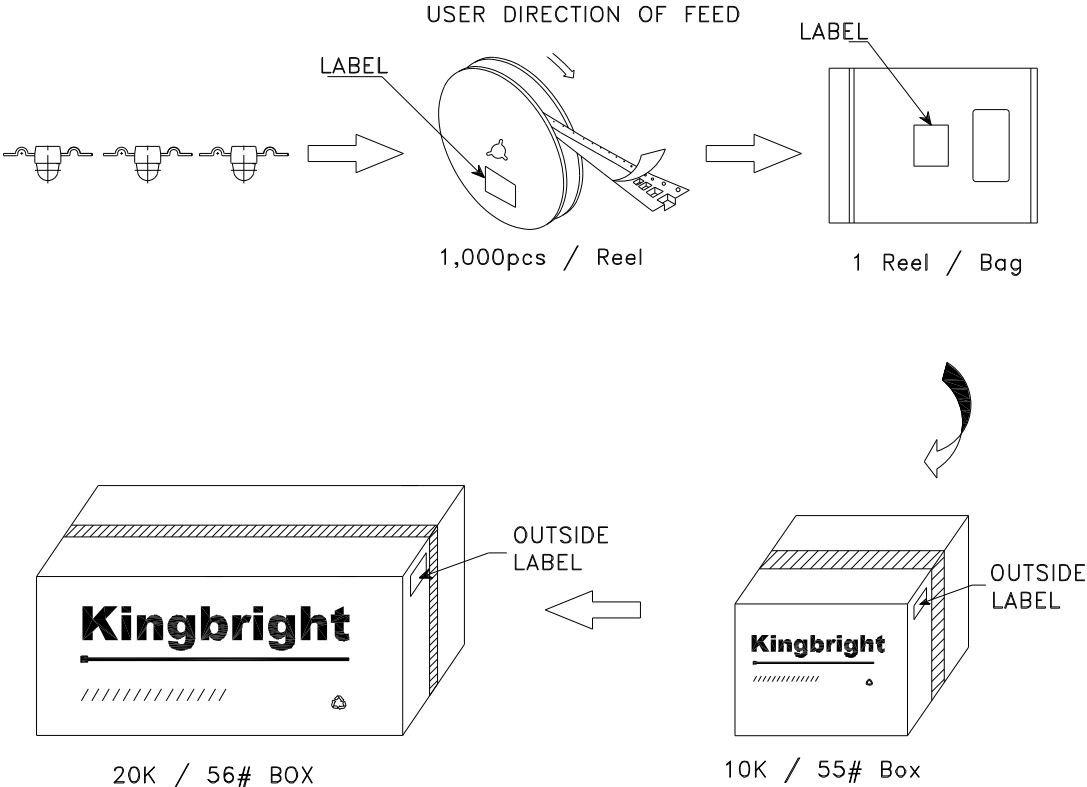



Tape Dimensions (Units : mm)



PACKING & LABEL SPECIFICATIONS

AM27MGC08



| | |
|---|---|
| Kingbright | |
| P/NO: AM27xxx08 | |
| QTY: 1,000 pcs | Q.C. <div>Q C XX XX XXXX PASSED</div> |
| S/N: XXXX | |
| CODE: XXX | |
| LOT NO:  XXXXXXXXXXXXXXXXXXXX | |
| RoHS Compliant | |